IXYS

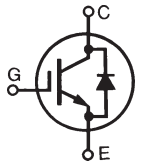
Preliminary Technical Information

High Voltage, High Gain BIMOSFET™ Monolithic Bipolar MOS Transistor

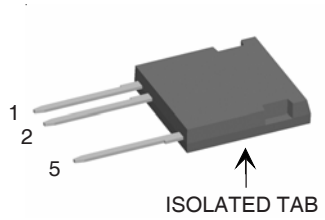
IXBF32N300

V_{CES} = 3000V
I_{C90} = 22A
$V_{CE(sat)} \leq$ 3.2V

(Electrically Isolated Tab)



ISOPLUS i4-Pak™



1 = Gate 5 = Collector
2 = Emitter

Symbol	Test Conditions	Maximum Ratings	
V_{CES}	T_C = 25°C to 150°C	3000	V
V_{CGR}	T_J = 25°C to 150°C, R_{GE} = 1MΩ	3000	V
V_{GES}	Continuous	± 20	V
V_{GEM}	Transient	± 30	V
I_{C25}	T_C = 25°C	40	A
I_{C90}	T_C = 90°C	22	A
I_{CM}	T_C = 25°C, 1ms	250	A
SSOA (RBSOA)	V_{GE} = 15V, T_{VJ} = 125°C, R_G = 10Ω Clamped Inductive Load	I_{CM} = 80 $V_{CES} \leq$ 2400	A V
P_C	T_C = 25°C	160	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
T_L	1.6mm (0.062 in.) from Case for 10s	300	°C
T_{SOLD}	Plastic Body for 10 seconds	260	°C
F_C	Mounting Force	20..120 / 4.5..27	Nm/lb.in.
V_{ISOL}	50/60Hz, 1 Minute	3000	V
Weight		5	g

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
BV_{CES}	I_C = 250μA, V_{GE} = 0V	3000			V
$V_{GE(th)}$	I_C = 250μA, V_{CE} = V_{GE}	2.5		5.0	V
I_{CES}	V_{CE} = 0.8 • V_{CES}, V_{GE} = 0V			50	μA
	T_J = 125°C			2	mA
I_{GES}	V_{CE} = 0V, V_{GE} = ± 20V			±100	nA
$V_{CE(sat)}$	I_C = 32A, V_{GE} = 15V, Note 1		2.8	3.2	V
	T_J = 125°C		3.5		V

Features

- Silicon Chip on Direct-Copper Bond (DCB) Substrate
- Isolated Mounting Surface
- 3000V Electrical Isolation
- High Blocking Voltage
- International Standard Package
- Low Conduction Losses

Advantages

- Low Gate Drive Requirement
- High Power Density

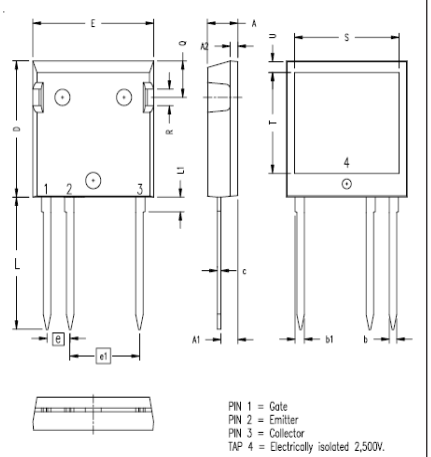
Applications:

- Switched-Mode and Resonant-Mode Power Supplies
- Uninterruptible Power Supplies (UPS)
- Laser Generators
- Capacitor Discharge Circuits
- AC Switches

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Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	I_C = 32A, V_{CE} = 10V, Note 1	16	26		S
C_{ies}	V_{CE} = 25V, V_{GE} = 0V, f = 1MHz		3140		pF
C_{oes}			124		pF
C_{res}			40		pF
Q_g	I_C = 32A, V_{GE} = 15V, V_{CE} = 1000V		142		nC
Q_{ge}			20		nC
Q_{gc}			57		nC
$t_{d(on)}$	**Resistive Switching Times, T_J = 25°C**		50		ns
t_r	I_C = 32A, V_{GE} = 15V		185		ns
$t_{d(off)}$	V_{CE} = 1250V, R_G = 2Ω		160		ns
t_f			720		ns
$t_{d(on)}$	**Resistive Switching Times, T_J = 125°C**		58		ns
t_r	I_C = 32A, V_{GE} = 15V		515		ns
$t_{d(off)}$	V_{CE} = 1250V, R_G = 2Ω		165		ns
t_f			630		ns
R_{thJC}				0.78	°C/W
R_{thCS}			0.15		°C/W

ISOPLUS i4-Pak™ (HV) (IXBF) Outline



SYM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	.190	.205	4.83	5.21
A1	.102	.118	2.59	3.00
A2	.046	.085	1.17	2.16
b	.045	.055	1.14	1.40
b1	.058	.068	1.47	1.73
C	.020	.029	0.51	0.74
D	.819	.840	20.80	21.34
E	.770	.799	19.56	20.29
e	.150 BSC		3.81 BSC	
e1	.450 BSC		11.43 BSC	
L	.780	.840	19.81	21.34
L1	.083	.102	2.11	2.59
Q	.210	.244	5.33	6.20
R	.100	.180	2.54	4.57
S	.660	.690	16.76	17.53
T	.590	.620	14.99	15.75
U	.065	.080	1.65	2.03

Reverse Diode

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
V_F	I_F = 32A, V_{GE} = 0V			2.1	V
t_{rr}	I_F = 16A, V_{GE} = 0V, -di_F/dt = 100A/μs		1.5		μs
I_{RM}	V_R = 100V, V_{GE} = 0V		33		A

Note 1: Pulse Test, t ≤ 300μs, Duty Cycle, d ≤ 2%.

PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from data gathered during objective characterizations of preliminary engineering lots; but also may yet contain some information supplied during a pre-production design evaluation. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

IXYS Reserves the Right to Change Limits, Test Conditions and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,850,072 4,881,106 4,931,844 5,017,508 5,034,796 5,049,961 5,063,307 5,187,117 5,237,481 5,381,025 5,486,715 6,162,665 6,259,123 B1 6,306,728 B1 6,404,065 B1 6,534,343 6,583,505 6,683,344 6,710,405 B2 6,710,463 6,727,585 6,759,692 6,771,478 B2 7,005,734 B2 7,063,975 B2 7,071,537 7,157,338B2

Fig. 1. Output Characteristics @ 25ºC

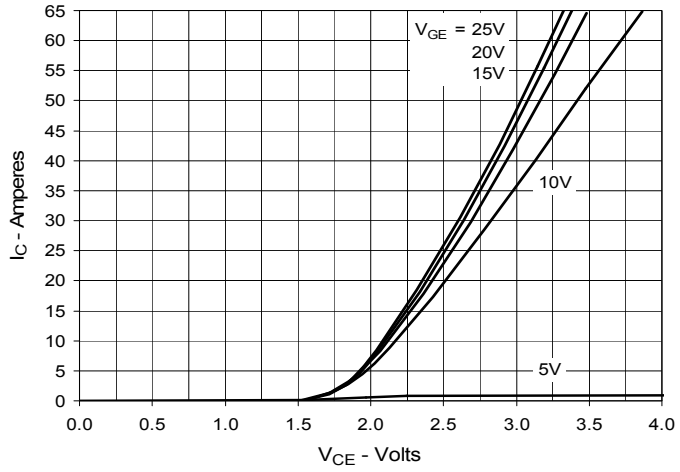


Fig. 2. Extended Output Characteristics @ 25ºC

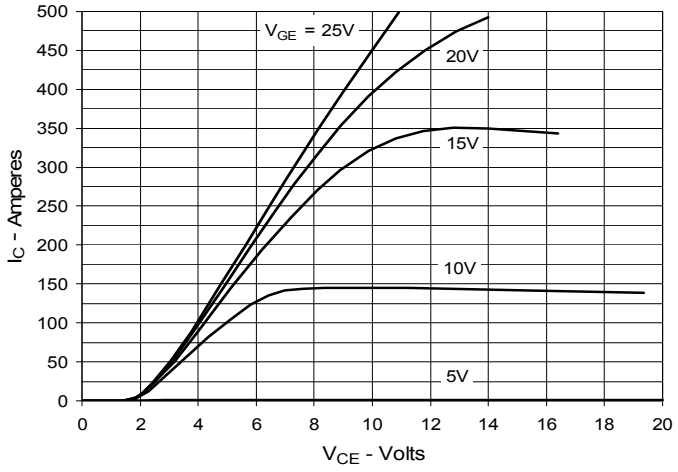


Fig. 3. Output Characteristics @ 125ºC

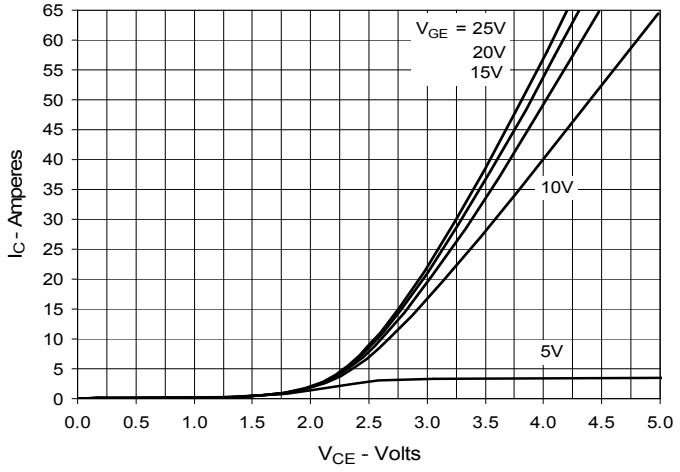


Fig. 4. Dependence of $V_{CE(sat)}$ on Junction Temperature

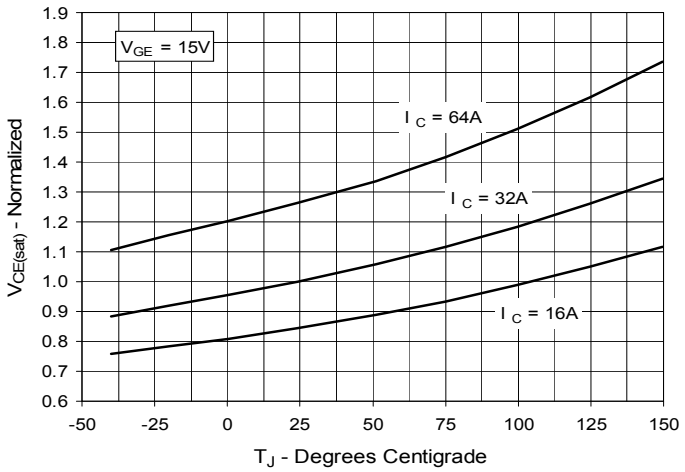


Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage

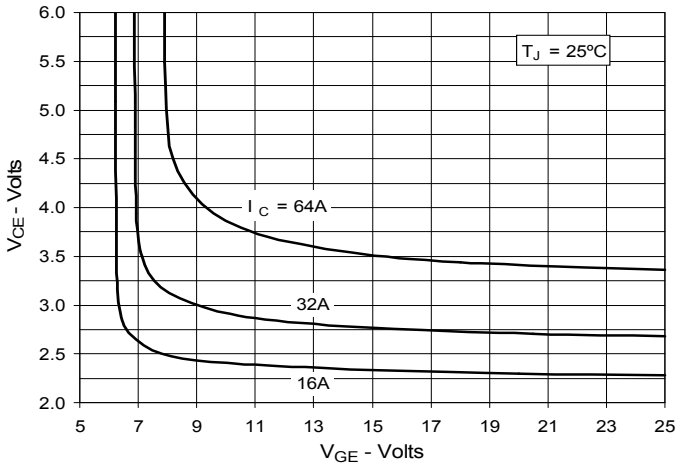
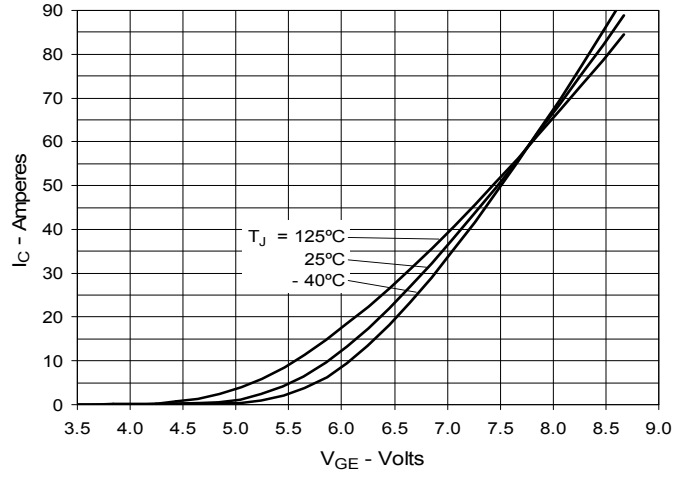


Fig. 6. Input Admittance



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Fig. 7. Transconductance

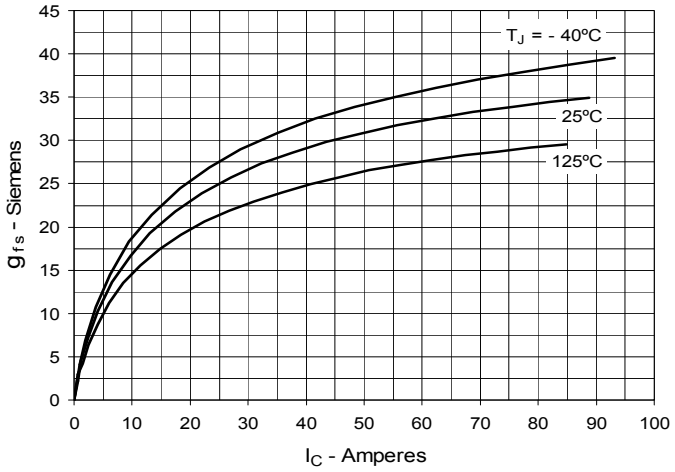


Fig. 8. Forward Voltage Drop of Intrinsic Diode

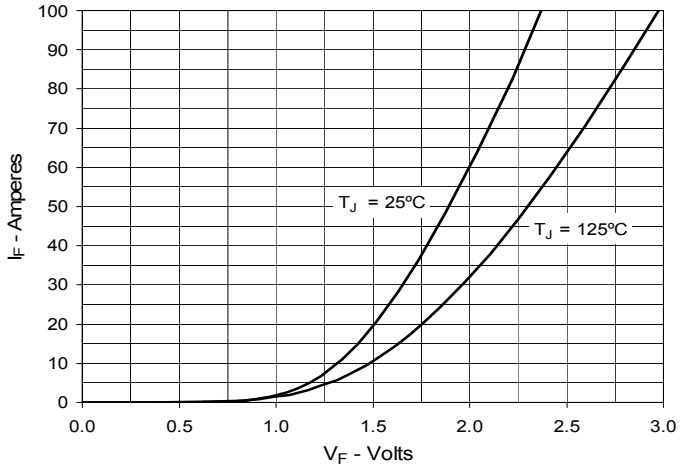


Fig. 9. Gate Charge

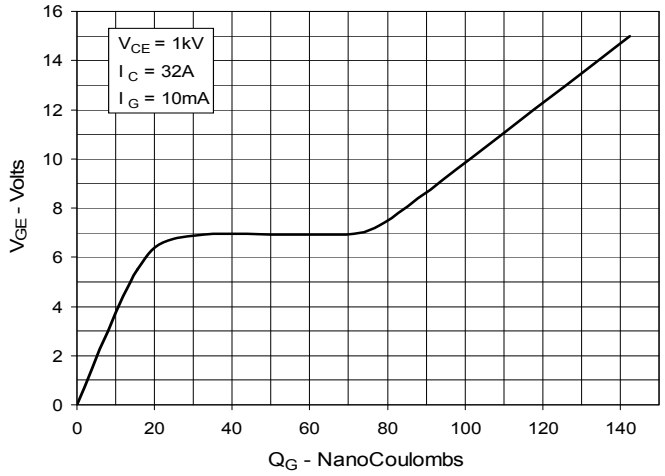


Fig. 10. Capacitance

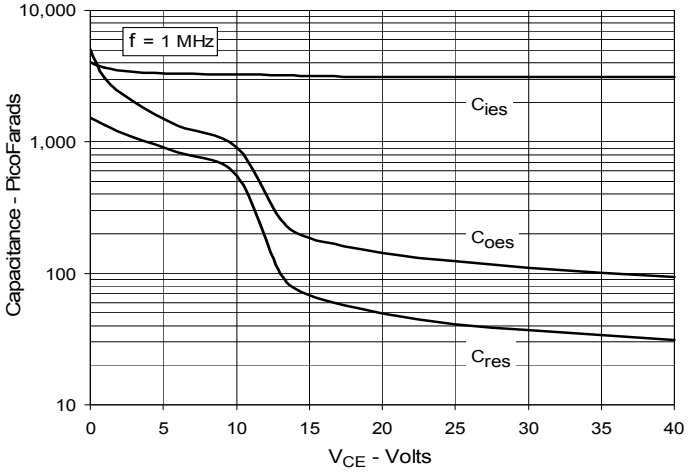


Fig. 11. Reverse-Bias Safe Operating Area

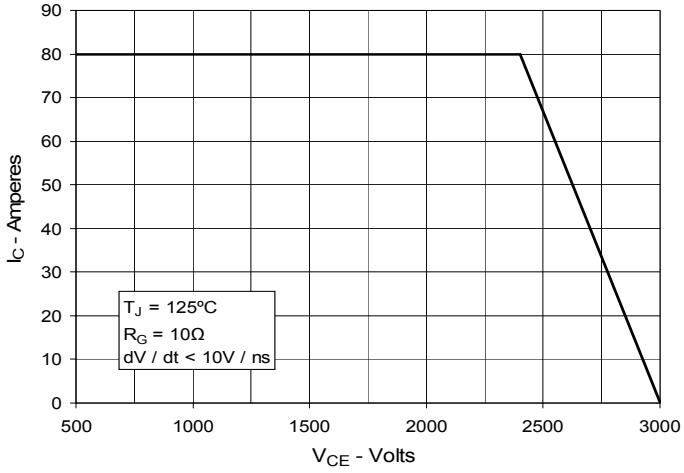
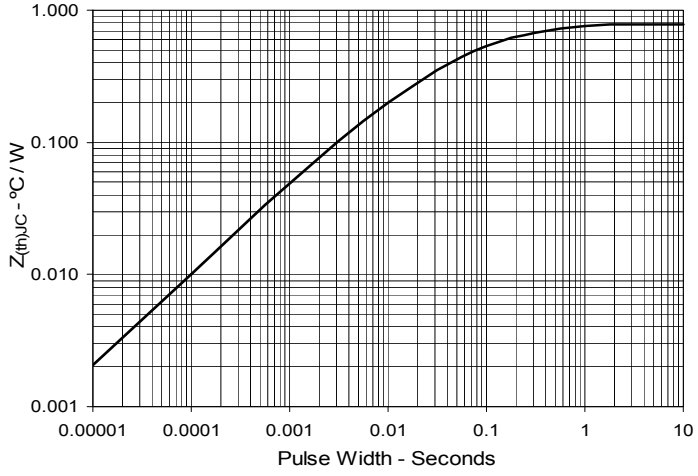


Fig. 12. Maximum Transient Thermal Impedance



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Fig. 13. Resistive Turn-on Rise Time vs. Junction Temperature

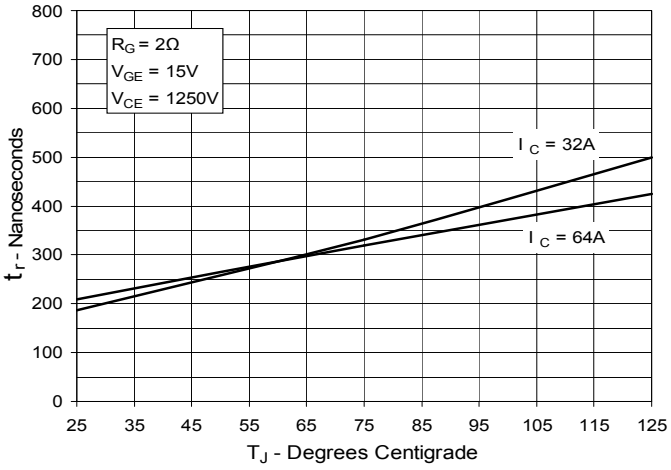


Fig. 14. Resistive Turn-on Rise Time vs. Drain Current

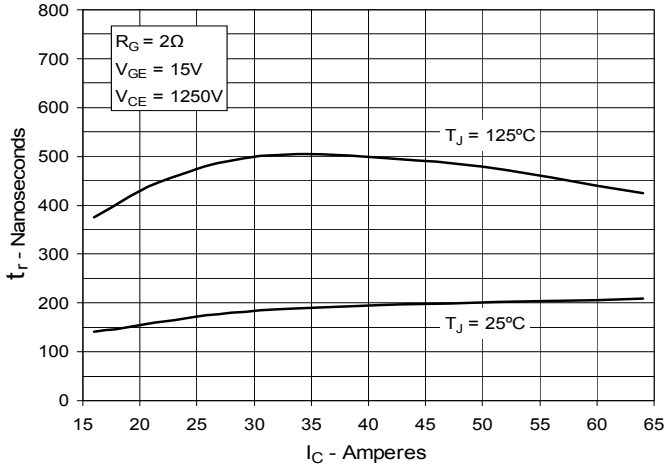


Fig. 15. Resistive Turn-on Switching Times vs. Gate Resistance

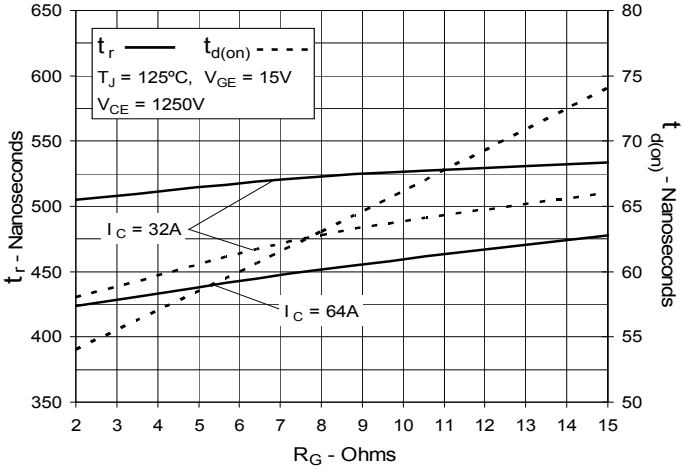


Fig. 16. Resistive Turn-off Switching Times vs. Junction Temperature

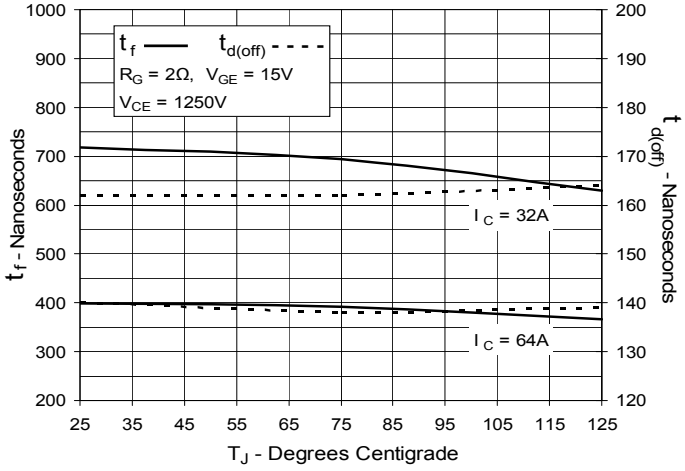


Fig. 17. Resistive Turn-off Switching Times vs. Drain Current

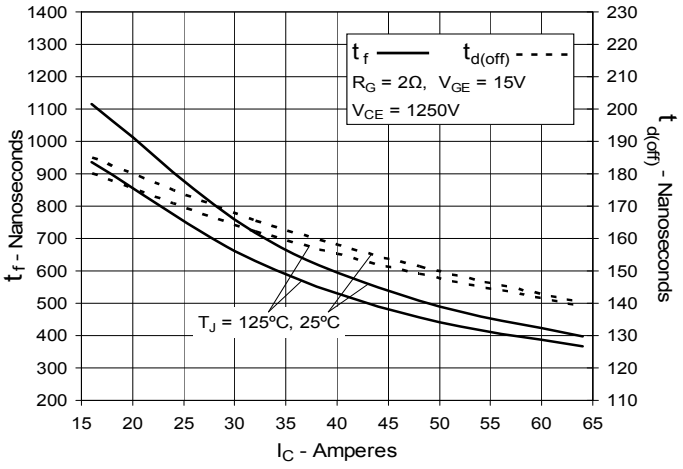
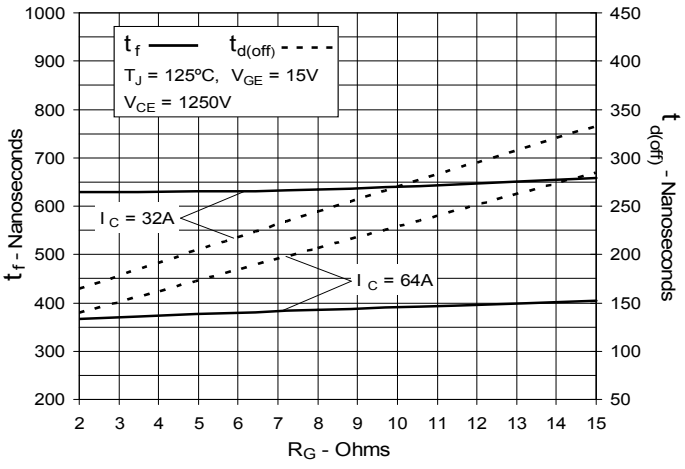


Fig. 18. Resistive Turn-off Switching Times vs. Gate Resistance



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